ABSTRACT

In an electric contact probe assembly, an electroconductive patch is attached to a part of the support sheet so as to cover a through hole formed in the support sheet from a front side thereof, and a base end of an electroconductive resilient probe member is attached to the patch. The patch is connected to a terminal of a circuit board both electrically and physically via a solder lump placed in the through hole. The patch may also be attached to the reverse side of the support sheet. In this case, the base end of the resilient probe member is partly received in the through hole. The contact probe assembly of the present invention is suited for a high density design comprising a large number of extremely small resilient probe members one next to the other while simplifying the fabrication process.

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